

## PATENT ABSTRACTS OF JAPAN

(11)Publication number : 08-083824

(43)Date of publication of application : 26.03.1998

(51)Int.Cl.

H01L 21/66  
G01R 1/073  
G01R 31/28

(21)Application number : 08-215869

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(22)Date of filing : 09.09.1994

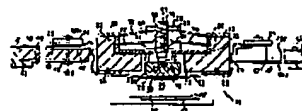
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## (54) PROBE EQUIPMENT

## (57)Abstract

PURPOSE: To bring a contactor of probe equipment into contact with an electrode pad without fail.

CONSTITUTION: Probe equipment has a setting stage 13 for a semiconductor wafer W and a printed wiring board 42 fitted with a support block 50 is provided above the stage. A flexible film-like probe card 21 is fitted so that it covers a recessed part 55 of the support block 50. The probe card 21 has a main region 27 wherein a contactor 28 to be brought into contact with an electrode pad EP of the wafer W is disposed. A hard rectangular frame 29 for giving flatness is joined on the rear side of the probe card 21. A pusher 71 is provided inside the recessed part 55 of the support block 50 and it comes into contact with the rear side of the probe card 21. The pusher 71 is disposed swingably at the lower end of the shaft 74 supported vertically. The shaft 74 is supported by the support block 50 through the intermediary of two coned disk springs 77 and 78.



## LEGAL STATUS

[Date of request for examination] 13.07.1998

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision  
of rejection or application converted registration]

[Date of final disposal for application]

[Patent number] 2978720

[Date of registration] 10.09.1999

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]